WAFER DICING/BONDING SHEET AND PROCESS FOR PRODUCING SEMICONDUCTOR DEVICE

ABSTRACT

The wafer dicing/bonding sheet of the present invention comprises a soft film, a pressure sensitive adhesive layer formed on the soft film, a processing film for polyimide type resin composed of a heat resistant resin which has been formed on the pressure sensitive adhesive layer and a polyimide adhesive layer formed on the processing film. It is preferred that the processing film be a polyethylene naphthalate film whose surface has been subjected to an alkyd release treatment. The present invention facilitates expansion to be conducted after the wafer dicing.

Figure 1